

ABSTRACT OF THE DISCLOSURE

The present invention provides a wire non-attachment inspection system (100) of a semiconductor device (10), wherein: the wire non-attachment inspection system (100) comprises an ultrasonic oscillator (40), an ultrasonic transducer (42), a camera (45),
5 a display (48), and a control unit (50); and the control unit (50) calculates the difference in image between one frame of a captured video and a previous frame before the one frame, and displays, on the display, an image of a wire for which the difference exceeds a prescribed threshold value so as to be displayed differently than the image of another wire.

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FIGURE 1